ISOCC 2026

23rd International SoC Design Conference

October 11-14, 2026

Songdo ConvensiA, Incheon, Korea

http://www.isocc.org



Conference Theme

"From Silicon to Physical Intelligence: Heterogeneous SoC Innovations"

About ISOCC

ISOCC has established a long tradition as an annual conference providing the premier SoC design forum for worldwide researchers from academia and industries. Since its inception, ISOCC has been continuing to showcase the most recent innovations and trends in the semiconductor system-on-a-chip area with active participations from worldwide researchers in academia, industry, and institutes. ISOCC 2026 welcomes technical papers in the field of semiconductor circuits and systems presenting new advanced concept and developments in analog and digital circuit and system design, theory, simulation, modeling, experimental implementations and experiences, and emerging technologies in the system-on-a-chip area.

The 23rd International SoC Conference (ISOCC 2026) will be held in Incheon, South Korea. Incheon, located on the northwestern coast of the Korean Peninsula, is South Korea's gateway city to the world and a leading hub of international business, culture, and innovation. Home to the award-winning Incheon International Airport and the state-of-the-art Songdo International Business District, Incheon combines advanced infrastructure with scenic attractions such as coastal parks, islands, and cultural heritage sites, offering participants a unique blend of global accessibility and local charm.

ISOCC 2026 is financially co-sponsored by IEEE CAS Society. All accepted papers will be published in the conference proceedings and will be submitted for inclusion in IEEE Xplore. We also welcome proposals for tutorials and special sessions.

Venue: Songdo ConvensiA

Address: Songdo ConvensiA, 123 Central Street, Yeonsu-gu, Incheon, 21998, Korea
Website: https://songdoconvensia.visitincheon.or.kr/
Tel: +82 32-210-1114 Fax: +82 32-210-1005

Key Organizing Committee

General Chair
- **Yongmin Kim** *(Hongik University, South Korea)*

General Co-Chairs
- **Yongfu Li** *(Shanghai Jiao Tong University, China)*

General Vice Chair
- **Minkyu Je** *(KAIST, Korea)*

Technical Program Committee Chair
- **Ilku Nam** *(Pusan National University, Korea)*

Technical Program Committee Co-chair
- **Yoko Uwate** *(Tokushima University, Japan)*

Conference Management Chairs
- **Hyun Kim** *(SEOULTECH, Korea)*
- **Sunmean Kim** *(Kyungbuk National University, Korea)*

Important Date

June 26, 2026	~~June 26, 2026~~ July 10, 2026	~~July 31, 2026~~ August 7, 2026	August 21, 2026	October 11-13, 2026
Submission of Special Session and Tutorial Proposals	Submission of Full Papers	Notification of Acceptance of Full Papers	Author Registration	On-site Registration

Topics of Interest

- Analog Circuits
- Analog Circuits
- Amplifiers and Filters
- Power Management Circuits

- Data Converters
- Analog-to-Digital Converter
- Digital-to-Analog Converters
- Analog Circuits for Data Converters

- RF/Wireless
- RF Circuits and Transceivers
- Microwave and Millimeter-Wave Circuits
- Wireless Communication Circuits

- Wireline
- High-Speed Interface
- Wireline Link

- Digital Circuits, Architecture, and Systems
- Multimedia Systems and Image Processing Applications
- Digital Signal Processing and Communication Systems
- Embedded Software and Systems
- Hardware Security Circuits
- Memory Circuits and Systems

- Machine Learning and AI
- Machine Learning/AI Algorithms
- Systems and Architectures for Machine Learning/AI
- Machine Learning Accelerators and Circuits
- Near-Memory and In-Memory Computation for AI
- Neuromorphic Architectures and Processors
- Physical AI Circuits and Systems

- SoC Design Methodology and CAD
- System-Level Modeling and Design Methodology
- Logic/High-Level Synthesis and Optimization
- Physical Design
- Design for Manufacturability and Reliability
- Testing, Validation, Simulation and Verification

- Circuits and Systems for Emerging Technologies
- Neuromorphic and Emerging Devices and Circuits
- Sensory and Biomedical Circuits and Systems
- Automotive Circuits and Systems
- IoT/IoE Circuits and Systems
- Heterogeneous Integration, 2.5D/3D Integration, and Advanced Packaging of Circuit Systems

Secretariat

E-mail: secretary@isocc.org Tel: +82-2-757-0981